

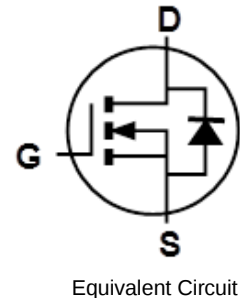
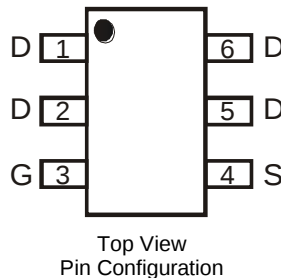
## Product Summary

| $V_{(BR)DSS}$ | $R_{DS(ON)} \text{ Max}$      | $I_D$<br>$T_A = +25^\circ\text{C}$ |
|---------------|-------------------------------|------------------------------------|
| 60V           | 44mΩ @ $V_{GS} = 10\text{V}$  | 5.0A                               |
|               | 60mΩ @ $V_{GS} = 4.5\text{V}$ | 4.3A                               |

## Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance ( $R_{DS(ON)}$ ), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- DC-DC Converters
- Power Management Functions
- Backlighting



## Features and Benefits

- 100% Unclamped Inductive Switch (UIS) Test in Production
- Low Input Capacitance
- Low On-Resistance
- Fast Switching Speed
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 standards for High Reliability**
- **PPAP Capable (Note 4)**

## Mechanical Data

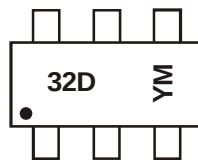
- Case: TSOT26
- Case Material: Molded Plastic, "Green" Molding Compound.  
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Tin Finish Annealed over Copper Leadframe.  
Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.013 grams (Approximate)

## Ordering Information (Note 5)

| Part Number    | Case   | Packaging          |
|----------------|--------|--------------------|
| DMN6040SVTQ-7  | TSOT26 | 3,000/Tape & Reel  |
| DMN6040SVTQ-13 | TSOT26 | 10,000/Tape & Reel |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. Automotive products are AEC-Q101 qualified and are PPAP capable. Please refer to [http://www.diodes.com/quality/product\\_compliance\\_definitions/](http://www.diodes.com/quality/product_compliance_definitions/).
  5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



32D = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: X = 2010)  
 M = Month (ex: 9 = September)

### Date Code Key

Date Code Key

| Year | 2010 | ... | 2017 | 2018 | 2019 | 2020 | 2021 | 2022 | 2023 | 2024 | 2025 |
|------|------|-----|------|------|------|------|------|------|------|------|------|
| Code | X    | ... | E    | F    | G    | H    | I    | J    | K    | L    | M    |

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code  | 1   | 2   | 3   | 4   | 5   | 6   | 7   | 8   | 9   | O   | N   | D   |

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic                                          |              |                                                  | Symbol           | Value      | Units |
|---------------------------------------------------------|--------------|--------------------------------------------------|------------------|------------|-------|
| Drain-Source Voltage                                    |              |                                                  | V <sub>DSS</sub> | 60         | V     |
| Gate-Source Voltage                                     |              |                                                  | V <sub>GSS</sub> | ±20        | V     |
| Continuous Drain Current (Note 7) V <sub>GS</sub> = 10V | Steady State | T <sub>A</sub> = +25°C<br>T <sub>A</sub> = +70°C | I <sub>D</sub>   | 5.0<br>4.0 | A     |
|                                                         | t < 10s      | T <sub>A</sub> = +25°C<br>T <sub>A</sub> = +70°C | I <sub>D</sub>   | 6.3<br>5.0 | A     |
| Continuous Drain Current (Note 7) V <sub>GS</sub> = 5V  | Steady State | T <sub>A</sub> = +25°C<br>T <sub>A</sub> = +70°C | I <sub>D</sub>   | 4.3<br>3.4 | A     |
|                                                         | t < 10s      | T <sub>A</sub> = +25°C<br>T <sub>A</sub> = +70°C | I <sub>D</sub>   | 5.4<br>4.3 | A     |
| Maximum Body Diode Forward Current (Note 7)             |              |                                                  | I <sub>S</sub>   | 2.1        | A     |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)      |              |                                                  | I <sub>DM</sub>  | 30         | A     |
| Avalanche Current (Note 8) L = 0.1mH                    |              |                                                  | I <sub>AR</sub>  | 14.2       | A     |
| Avalanche Energy (Note 8) L = 0.1mH                     |              |                                                  | E <sub>AR</sub>  | 10         | mJ    |

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic                                   |                        | Symbol                            | Value       | Units |
|--------------------------------------------------|------------------------|-----------------------------------|-------------|-------|
| Total Power Dissipation (Note 6)                 | T <sub>A</sub> = +25°C | P <sub>D</sub>                    | 1.2         | W     |
|                                                  | T <sub>A</sub> = +70°C |                                   | 0.75        |       |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady State           | R <sub>θJA</sub>                  | 106         | °C/W  |
|                                                  | t < 10s                |                                   | 69          | °C/W  |
| Total Power Dissipation (Note 7)                 | T <sub>A</sub> = +25°C | P <sub>D</sub>                    | 1.8         | W     |
|                                                  | T <sub>A</sub> = +70°C |                                   | 1.1         |       |
| Thermal Resistance, Junction to Ambient (Note 7) | Steady State           | R <sub>θJA</sub>                  | 68          | °C/W  |
|                                                  | t < 10s                |                                   | 44          | °C/W  |
| Thermal Resistance, Junction to Case (Note 7)    |                        | R <sub>θJC</sub>                  | 20          | °C/W  |
| Operating and Storage Temperature Range          |                        | T <sub>J</sub> , T <sub>STG</sub> | -55 to +150 | °C    |

- Notes:
6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
  7. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
  8. I<sub>AR</sub> and E<sub>AR</sub> rating are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C.

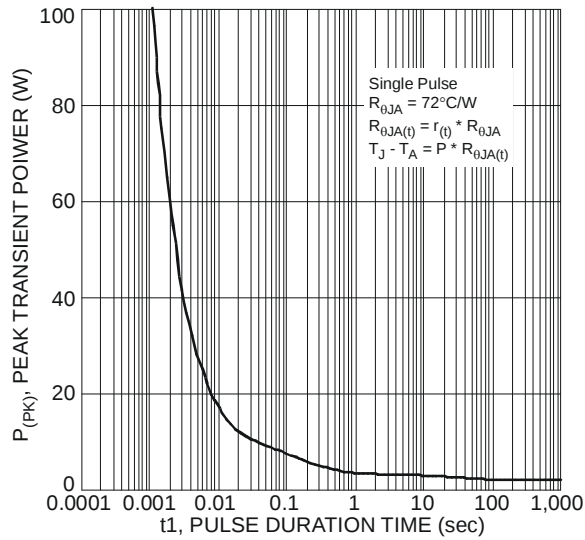


Fig. 1 Single Pulse Maximum Power Dissipation

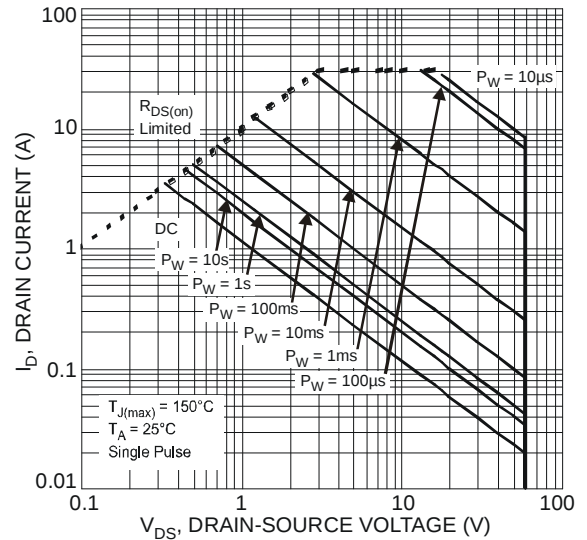


Fig. 2 SOA, Safe Operation Area

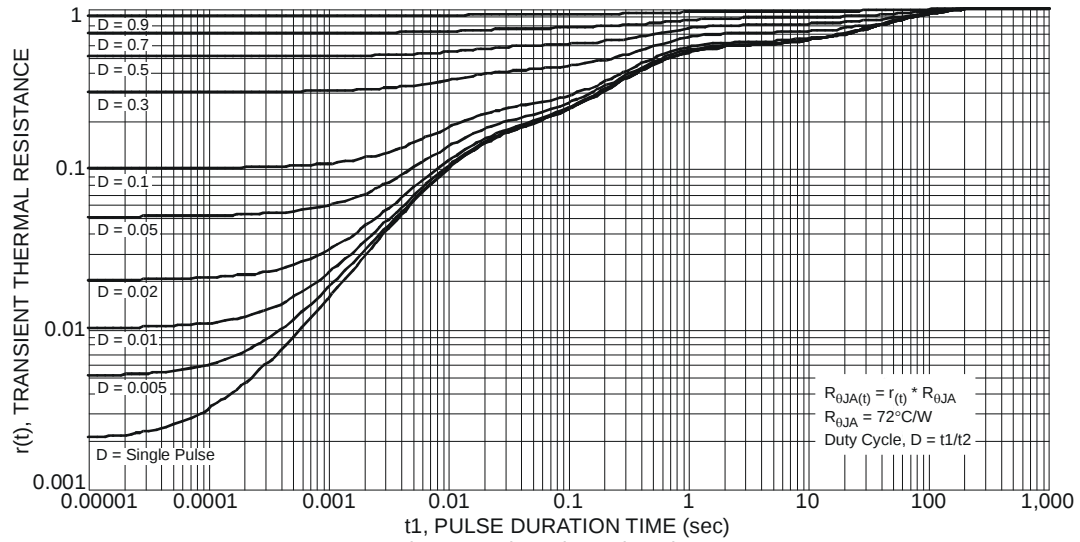


Fig. 3 Transient Thermal Resistance

**Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

| Characteristic                             | Symbol              | Min | Typ   | Max  | Unit | Test Condition                                                                              |
|--------------------------------------------|---------------------|-----|-------|------|------|---------------------------------------------------------------------------------------------|
| <b>OFF CHARACTERISTICS</b> (Note 9)        |                     |     |       |      |      |                                                                                             |
| Drain-Source Breakdown Voltage             | BV <sub>DSS</sub>   | 60  | —     | —    | V    | V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA                                                |
| Zero Gate Voltage Drain Current            | I <sub>DSS</sub>    | —   | —     | 100  | nA   | V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V                                                 |
| Gate-Source Leakage                        | I <sub>GSS</sub>    | —   | —     | ±100 | nA   | V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V                                                |
| <b>ON CHARACTERISTICS</b> (Note 9)         |                     |     |       |      |      |                                                                                             |
| Gate Threshold Voltage                     | V <sub>GS(TH)</sub> | 1   | —     | 3    | V    | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA                                  |
| Static Drain-Source On-Resistance          | R <sub>DS(ON)</sub> | —   | 30    | 44   | mΩ   | V <sub>GS</sub> = 10V, I <sub>D</sub> = 4.3A                                                |
|                                            |                     | —   | 35    | 60   |      | V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 4A                                                 |
| Forward Transfer Admittance                | Y <sub>FS</sub>     | —   | 4.5   | —    | S    | V <sub>DS</sub> = 10V, I <sub>D</sub> = 4.3A                                                |
| Diode Forward Voltage                      | V <sub>SD</sub>     | —   | 0.7   | 1.2  | V    | V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A                                                   |
| <b>DYNAMIC CHARACTERISTICS</b> (Note 10)   |                     |     |       |      |      |                                                                                             |
| Input Capacitance                          | C <sub>ISS</sub>    | —   | 1,287 | —    | pF   | V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V<br>f = 1.0MHz                                   |
| Output Capacitance                         | C <sub>OSS</sub>    | —   | 57    | —    |      |                                                                                             |
| Reverse Transfer Capacitance               | C <sub>RSS</sub>    | —   | 44    | —    |      |                                                                                             |
| Gate Resistance                            | R <sub>G</sub>      | —   | 1.2   | —    | Ω    | V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1.0MHz                                      |
| Total Gate Charge (V <sub>GS</sub> = 10V)  | Q <sub>G</sub>      | —   | 22.4  | —    | nC   | V <sub>DS</sub> = 30V, I <sub>D</sub> = 4.3A                                                |
| Total Gate Charge (V <sub>GS</sub> = 4.5V) | Q <sub>G</sub>      | —   | 10.4  | —    |      |                                                                                             |
| Gate-Source Charge                         | Q <sub>GS</sub>     | —   | 4.9   | —    |      |                                                                                             |
| Gate-Drain Charge                          | Q <sub>GD</sub>     | —   | 3.0   | —    |      |                                                                                             |
| Turn-On Delay Time                         | t <sub>D(ON)</sub>  | —   | 6.6   | —    | ns   | V <sub>GS</sub> = 10V, V <sub>DD</sub> = 30V, R <sub>G</sub> = 6Ω,<br>I <sub>D</sub> = 4.3A |
| Turn-On Rise Time                          | t <sub>R</sub>      | —   | 8.1   | —    |      |                                                                                             |
| Turn-Off Delay Time                        | t <sub>D(OFF)</sub> | —   | 20.1  | —    |      |                                                                                             |
| Turn-Off Fall Time                         | t <sub>F</sub>      | —   | 4.0   | —    |      |                                                                                             |
| Body Diode Reverse Recovery Time           | t <sub>RR</sub>     | —   | 18    | —    | ns   | I <sub>S</sub> = 4.3A, dI/dt = 100A/μs                                                      |
| Body Diode Reverse Recovery Charge         | Q <sub>RR</sub>     | —   | 11.9  | —    | nC   | I <sub>S</sub> = 4.3A, dI/dt = 100A/μs                                                      |

Notes: 9. Short duration pulse test used to minimize self-heating effect.  
10. Guaranteed by design. Not subject to product testing.

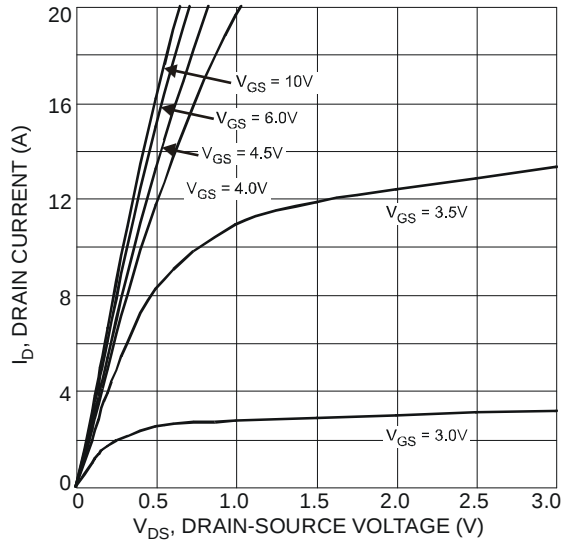


Fig. 4 Typical Output Characteristic

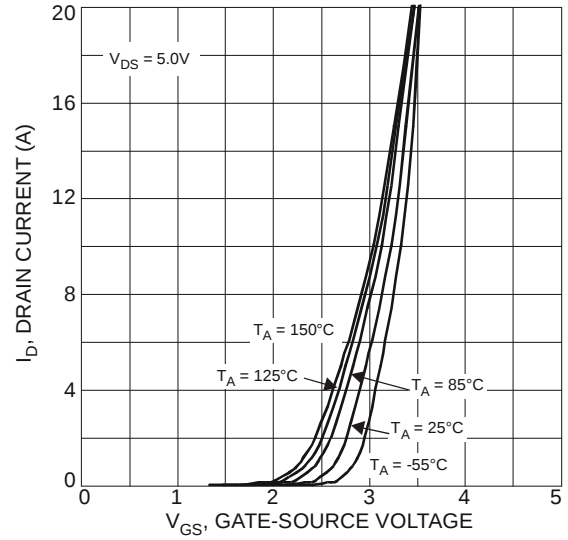


Fig. 5 Typical Transfer Characteristics

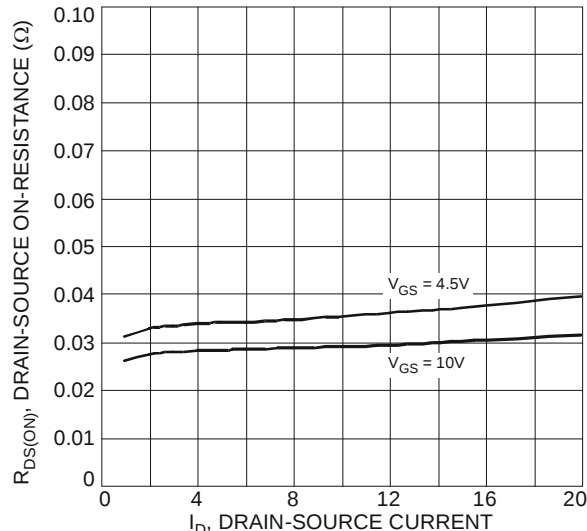


Fig. 6 Typical On-Resistance vs. Drain Current and Gate Voltage

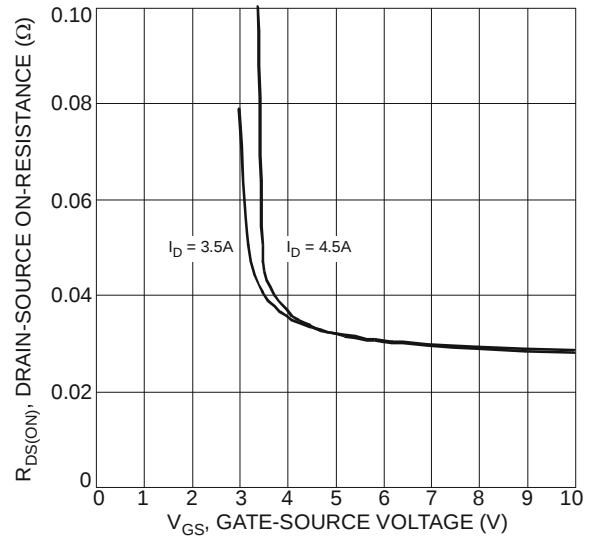


Fig. 7 Typical On-Resistance vs. Drain Current and Gate Voltage

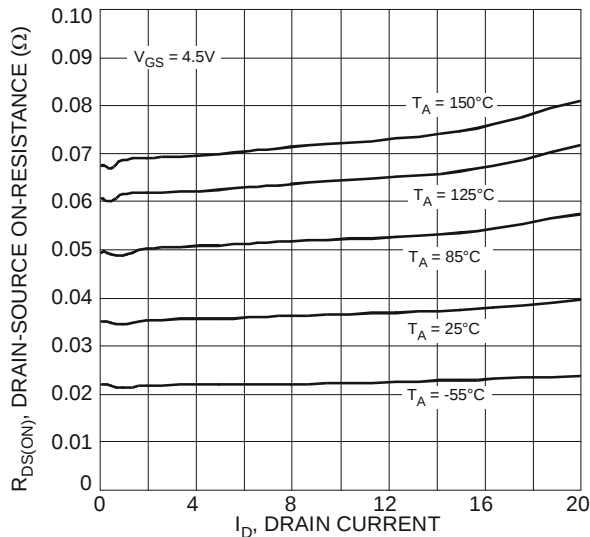


Fig. 8 Typical On-Resistance vs. Drain Current and Temperature

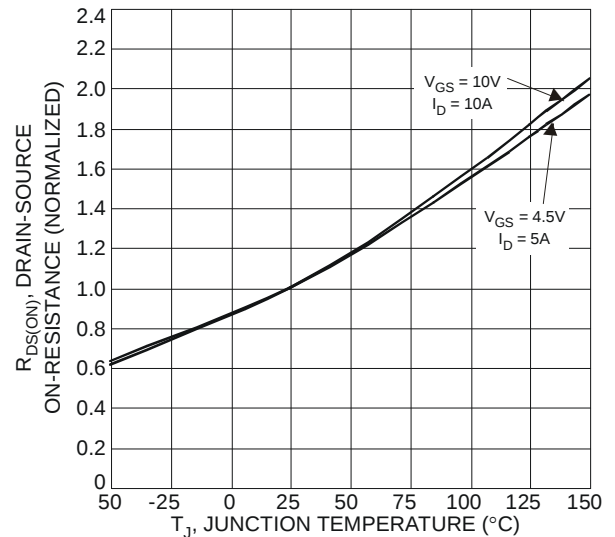


Fig. 9 On-Resistance Variation with Temperature

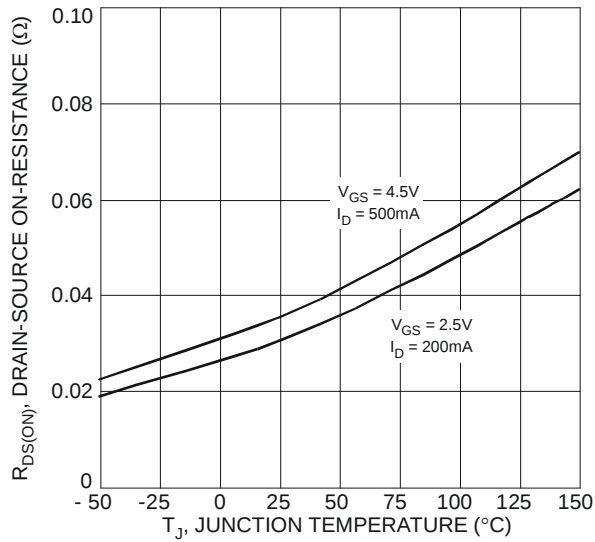


Fig. 10 On-Resistance Variation with Temperature

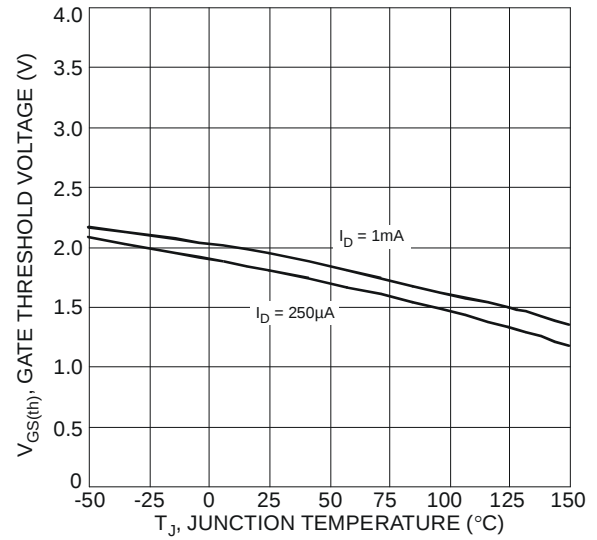


Fig. 11 Gate Threshold Variation vs. Ambient Temperature

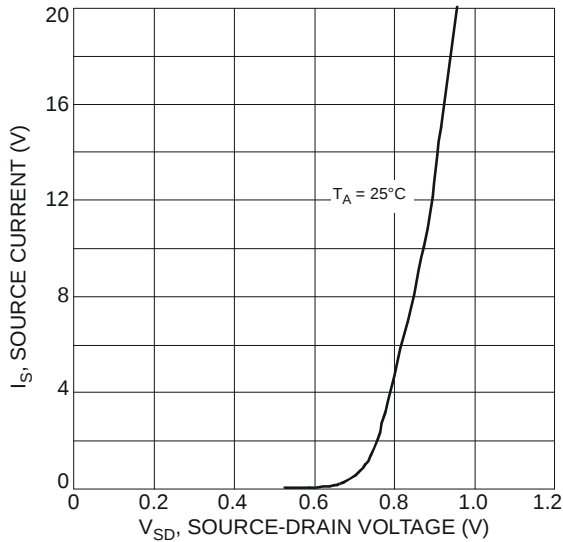


Fig. 12 Diode Forward Voltage vs. Current

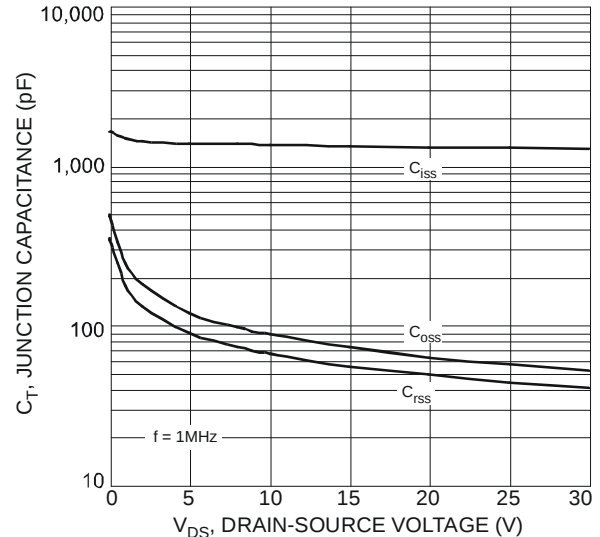


Fig. 13 Typical Junction Capacitance

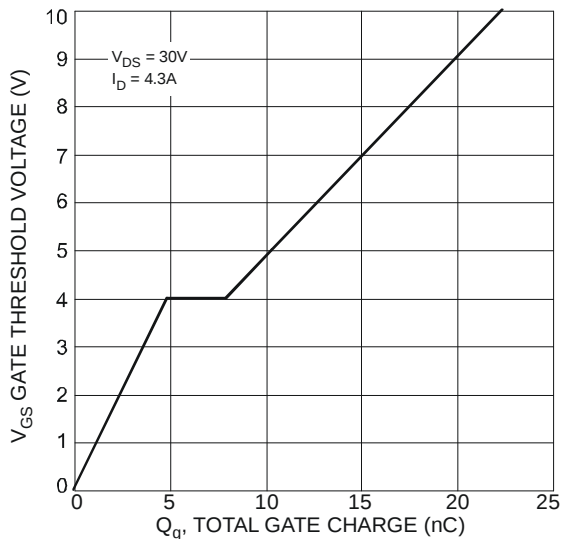
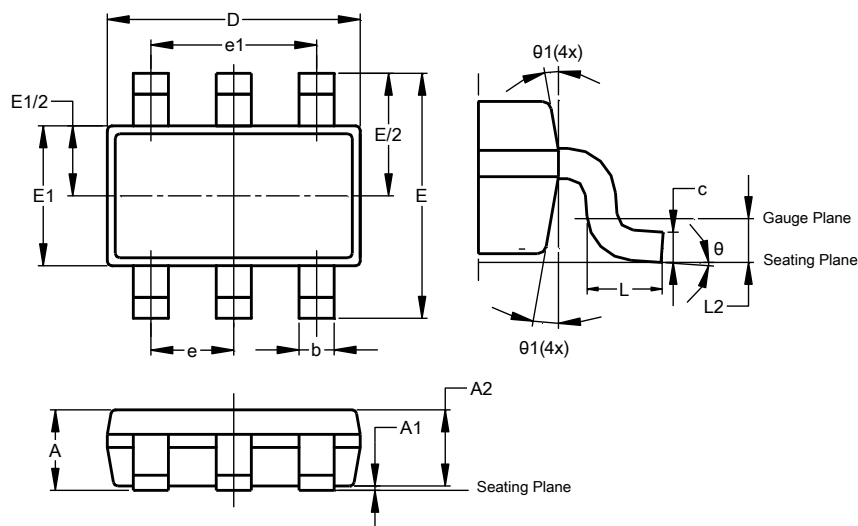


Fig. 14 Gate Charge

## Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.

**TSOT26**

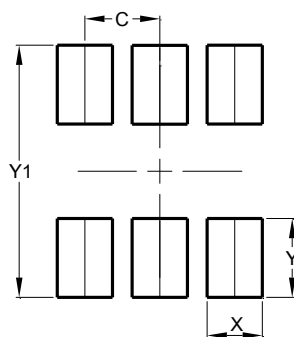


| TSOT26               |           |       |       |
|----------------------|-----------|-------|-------|
| Dim                  | Min       | Max   | Typ   |
| A                    | —         | 1.00  | —     |
| A1                   | 0.010     | 0.100 | —     |
| A2                   | 0.840     | 0.900 | —     |
| D                    | 2.800     | 3.000 | 2.900 |
| E                    | 2.800 BSC |       |       |
| E1                   | 1.500     | 1.700 | 1.600 |
| b                    | 0.300     | 0.450 | —     |
| c                    | 0.120     | 0.200 | —     |
| e                    | 0.950 BSC |       |       |
| e1                   | 1.900 BSC |       |       |
| L                    | 0.30      | 0.50  | —     |
| L2                   | 0.250 BSC |       |       |
| θ                    | 0°        | 8°    | 4°    |
| θ1                   | 4°        | 12°   | —     |
| All Dimensions in mm |           |       |       |

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.

**TSOT26**



| Dimensions | Value (in mm) |
|------------|---------------|
| C          | 0.950         |
| X          | 0.700         |
| Y          | 1.000         |
| Y1         | 3.199         |

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